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Attorney Docket No.: COOL-01901

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Daniel J. Lenehan et al.

Serial No.: 10/731,674

Filed: December 8, 2003

For: **PUMP AND FAN CONTROL
CONCEPTS IN A COOLING
SYSTEM**

) Group Art Unit: 3753

) Examiner:

) **TRANSMITTAL LETTER**

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313

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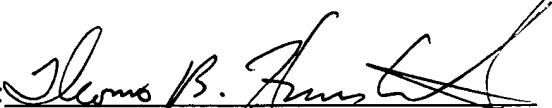
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The Commissioner is hereby authorized to charge any additional fee or credit overpayment to our Deposit Account No. 08-1275. **An originally executed duplicate of this transmittal is enclosed for this purpose.**

Respectfully submitted,
HAVERSTOCK & OWENS LLP

Dated: 3-30-04

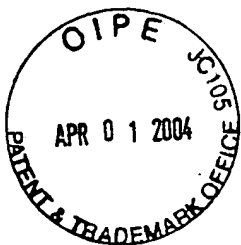
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STATEMENT**

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Sir:

The citations listed below, copies attached, may be material to the examination of the above-identified application, and are therefore submitted in compliance with the duty of disclosure defined in 37 C.F.R. §§ 1.56 and 1.97. The Examiner is requested to make these citations of official record in this application.

United States Patents or Published Patent Applications have been filed electronically (EFS ID #58124); (EFS ID #58126); and (EFS ID #58127). Applicants have become aware of the following printed publication which may be material to the examination of this application:

- Chinese Publication No. CN 97212126.9;
- Japanese Patent Abstract JP 2000-277540;
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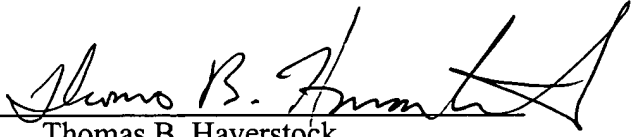
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Respectfully submitted,
HAVERSTOCK & OWENS LLP

Dated: 3-30-04

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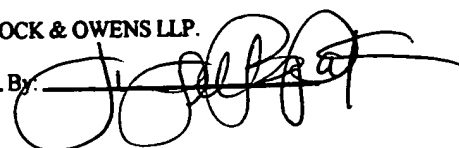
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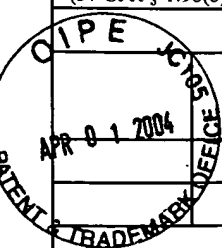
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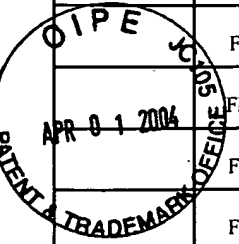
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